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FIG.2

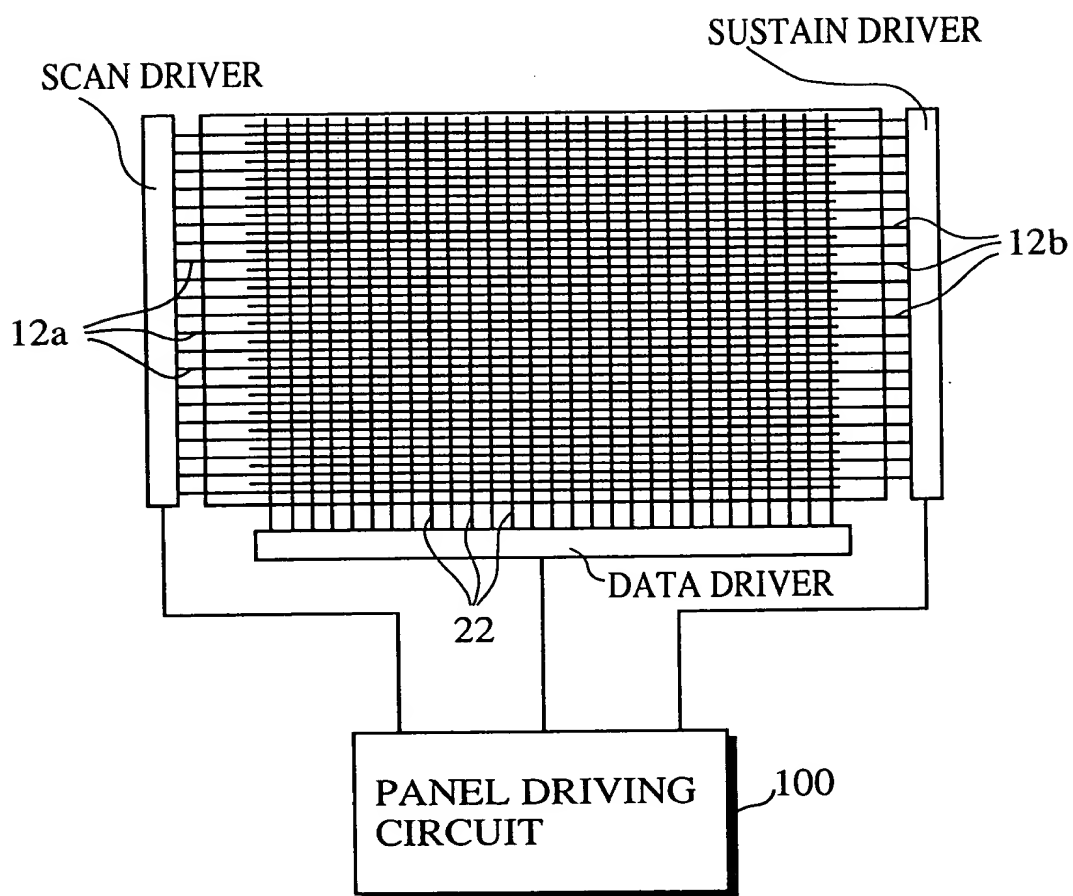


FIG.3

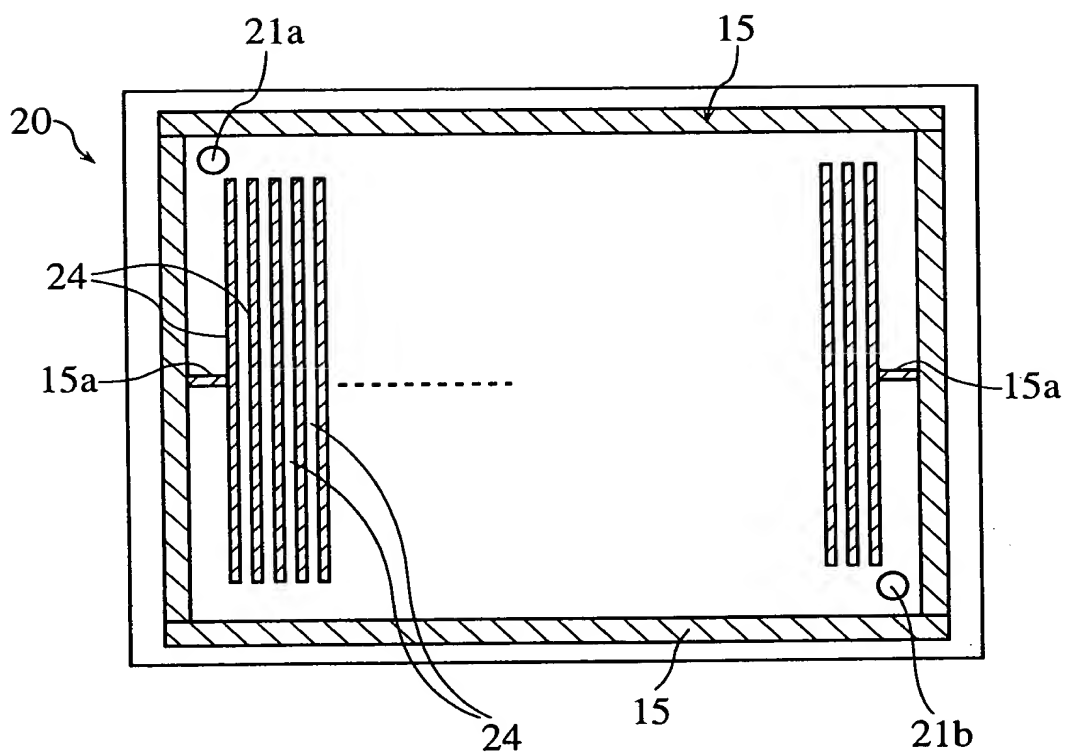
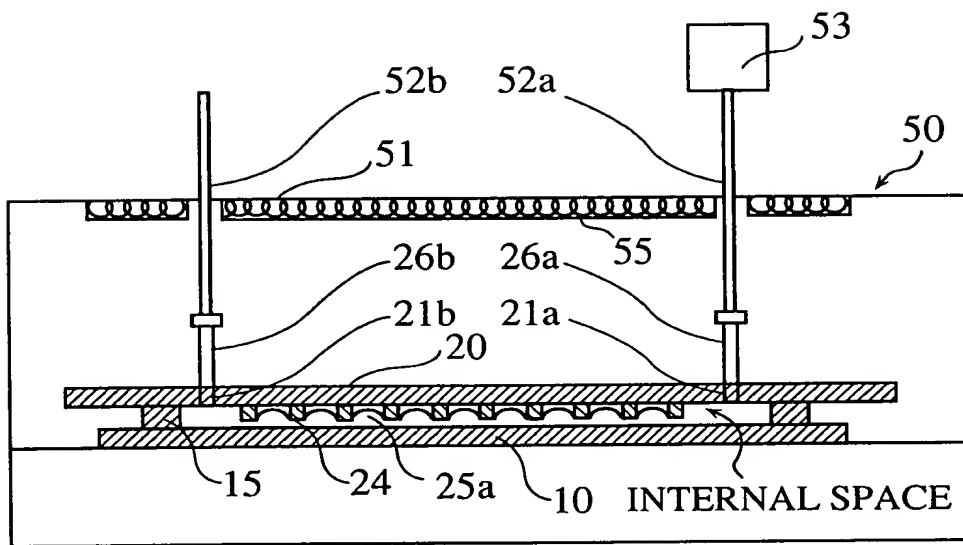


FIG.4



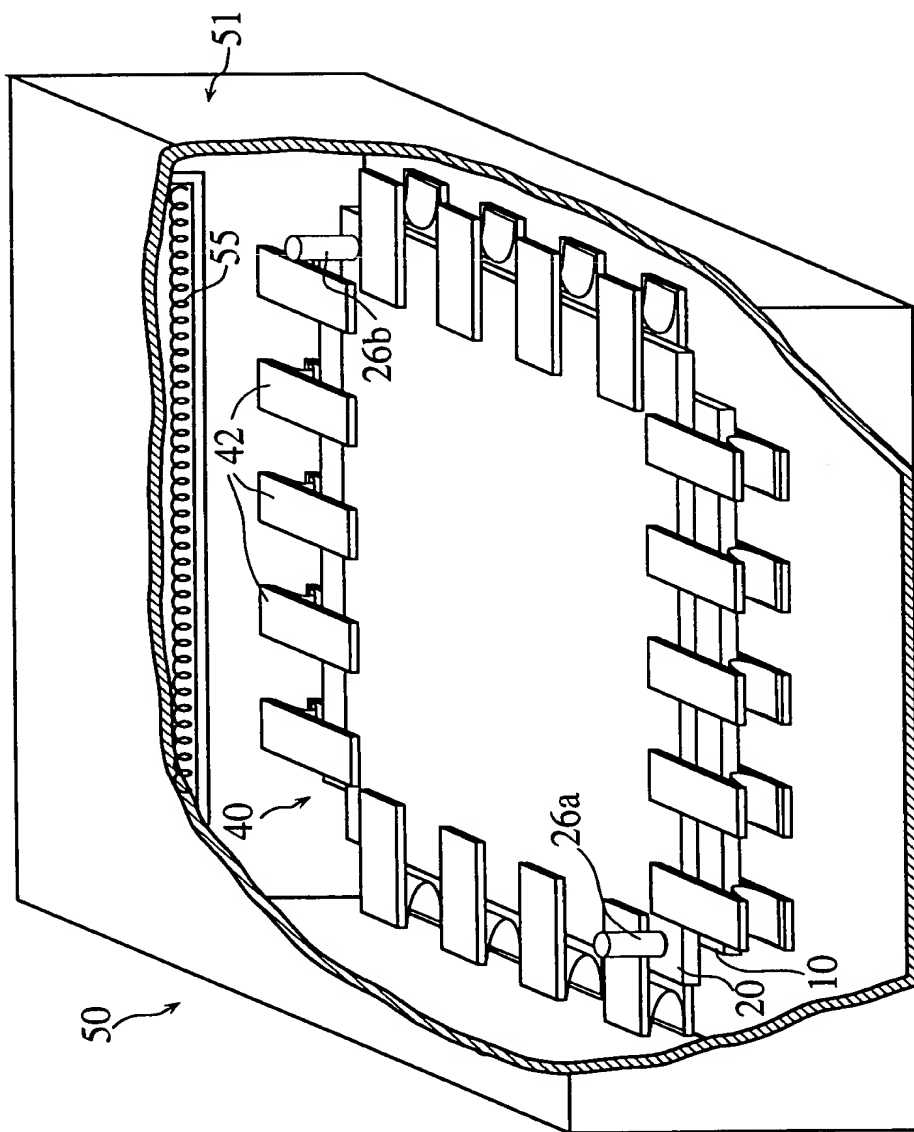


FIG. 5

FIG. 6

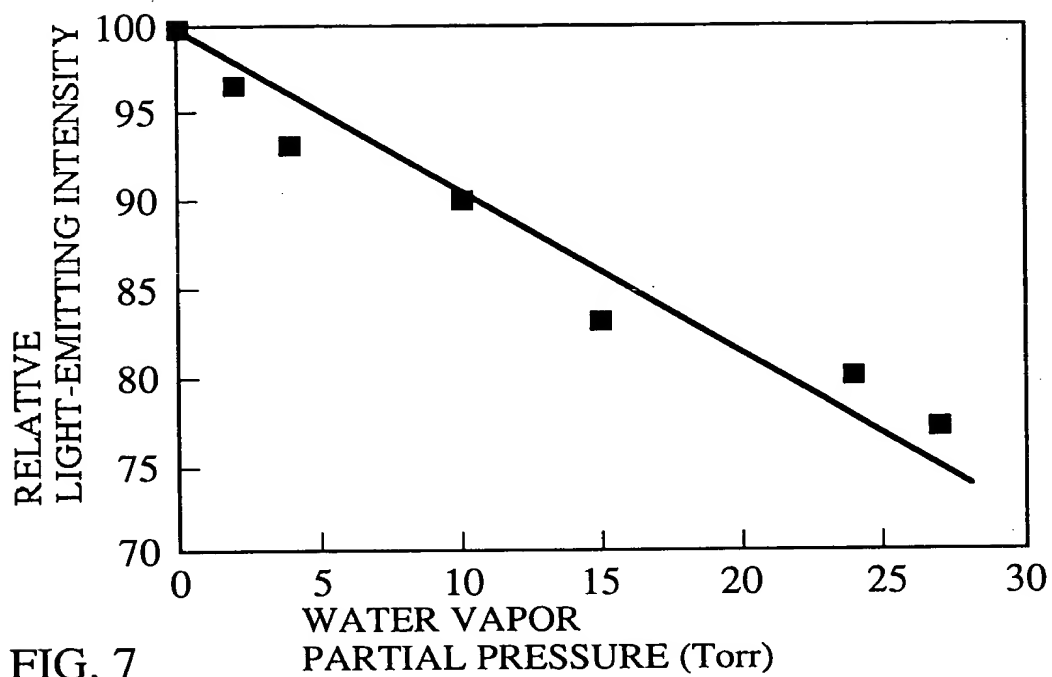


FIG. 7

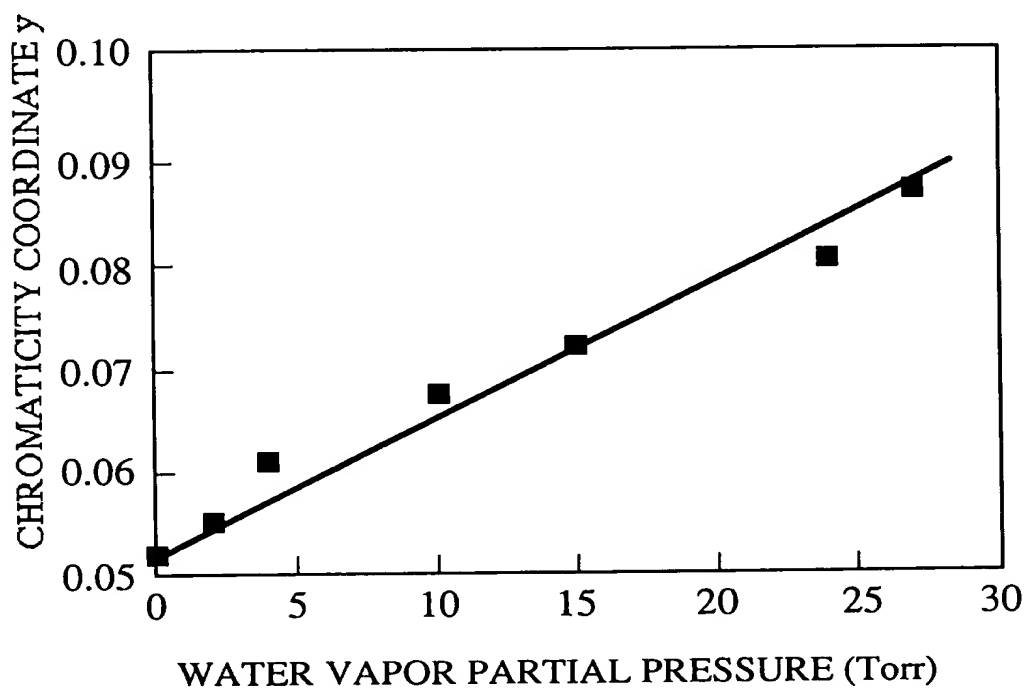


FIG. 8

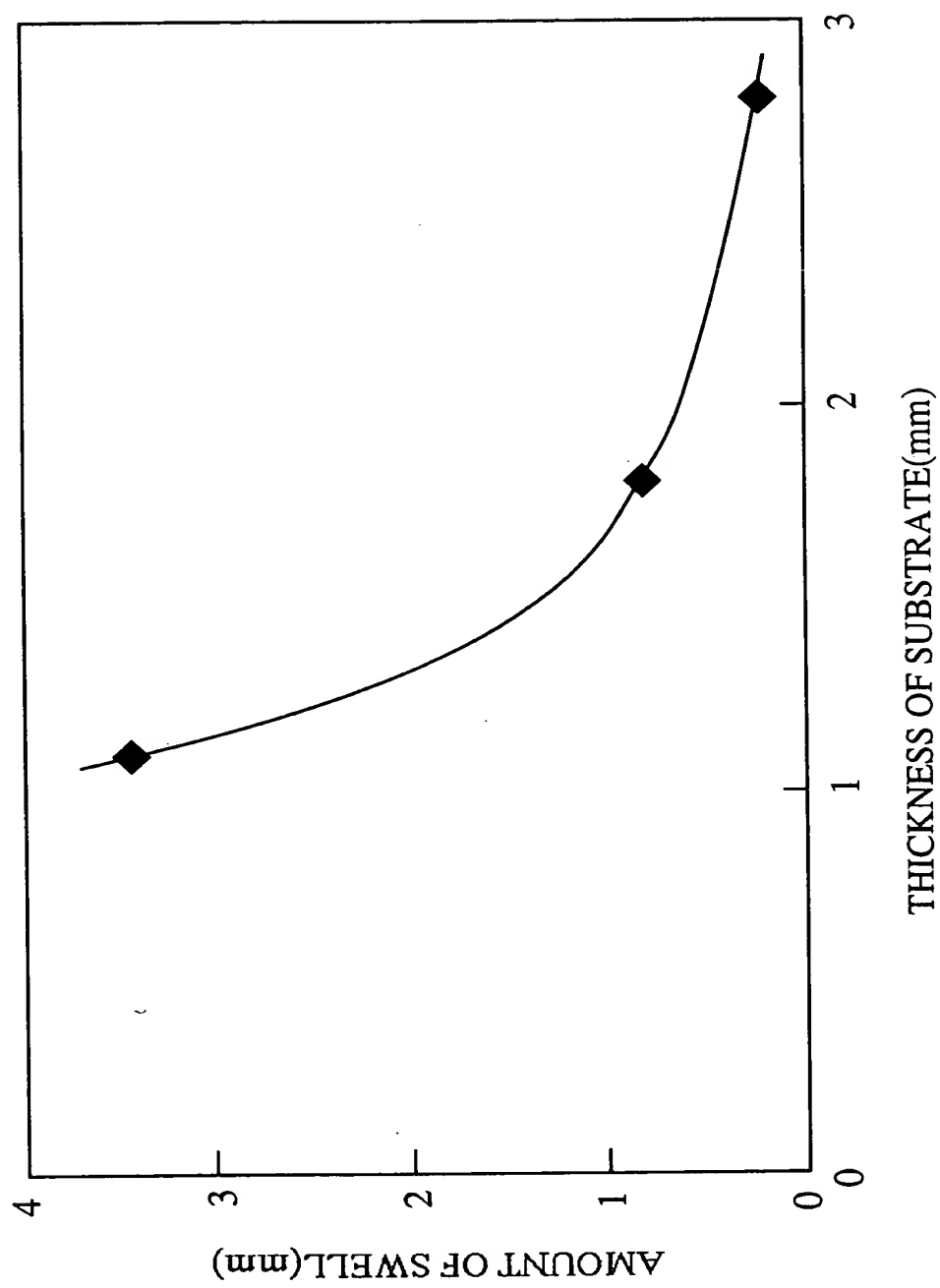




FIG. 9

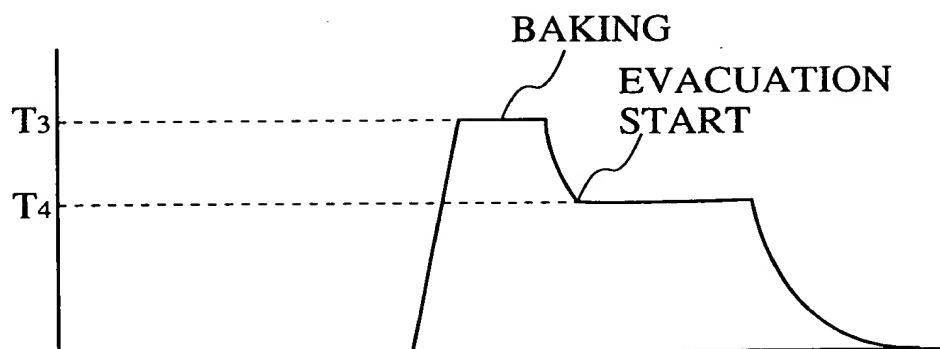


FIG. 10

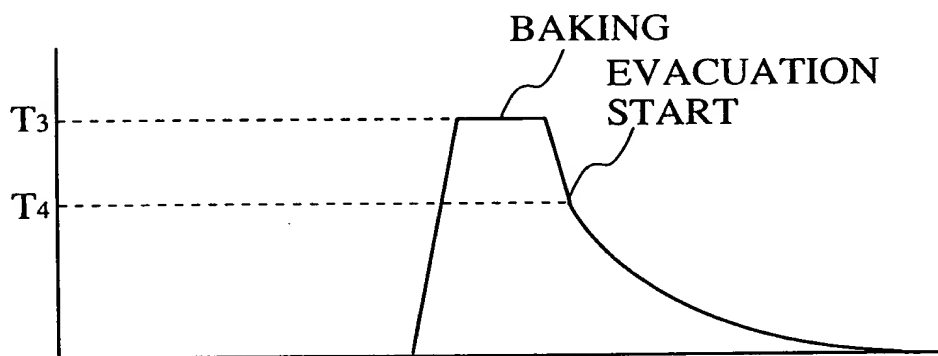


FIG. 11

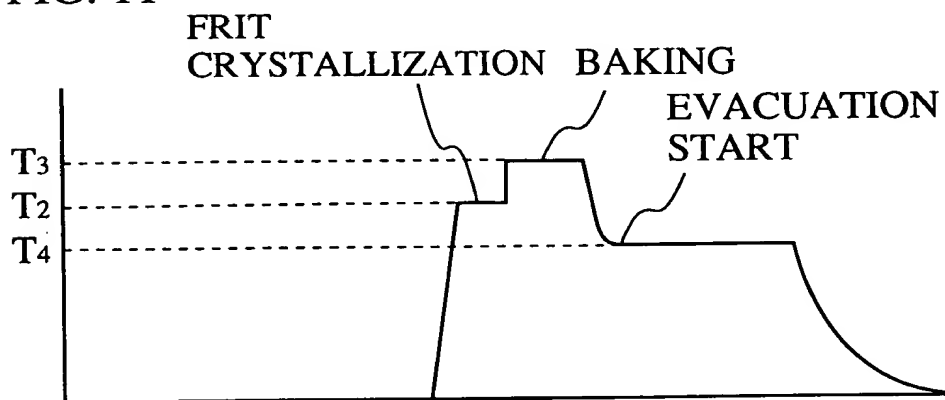
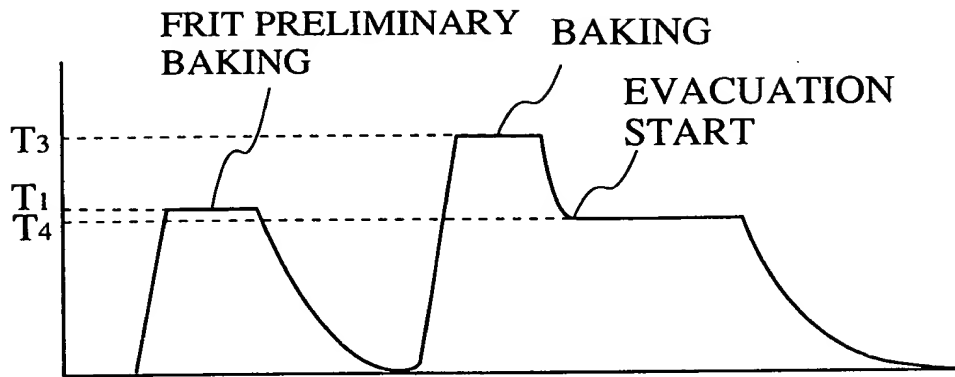


FIG. 12



The diagram illustrates a temperature profile for a glass frit bonding process. The vertical axis represents temperature, with markers  $T_1$ ,  $T_3$ , and  $T_2, T_4$ . The profile consists of several heating and cooling ramps. Key stages are labeled: BAKING (from  $T_1$  to  $T_3$ ), GLASS FRIT PRELIMINARY BAKING (from  $T_3$  to  $T_2, T_4$ ), BONDING (from  $T_2, T_4$  to  $T_3$ ), and EVACUATION START (from  $T_3$  to  $T_2, T_4$ ). The profile shows a series of heating and cooling cycles, with the temperature rising to  $T_3$  during BAKING and BONDING, and rising to  $T_2, T_4$  during GLASS FRIT PRELIMINARY BAKING and EVACUATION START.

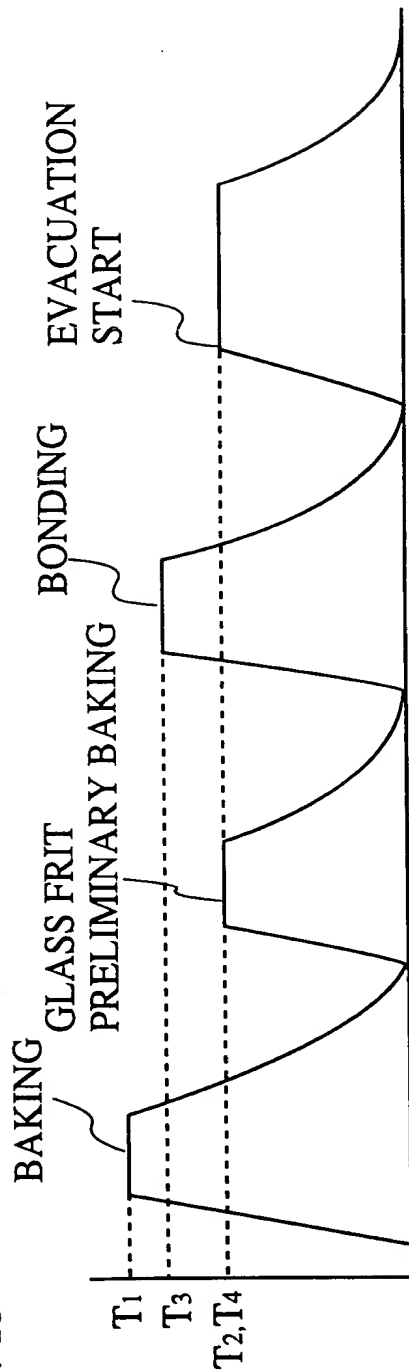




FIG. 15

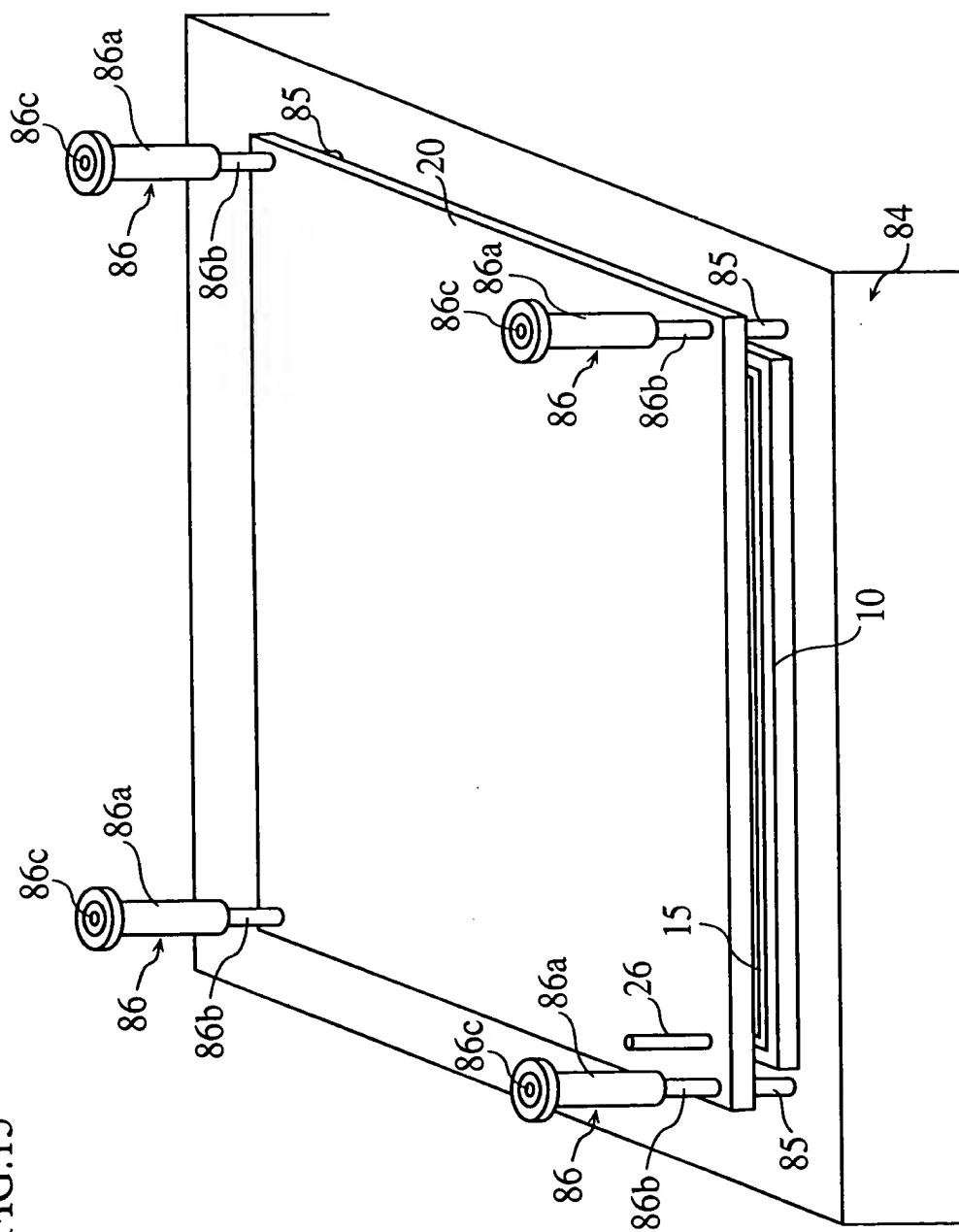


FIG.16A

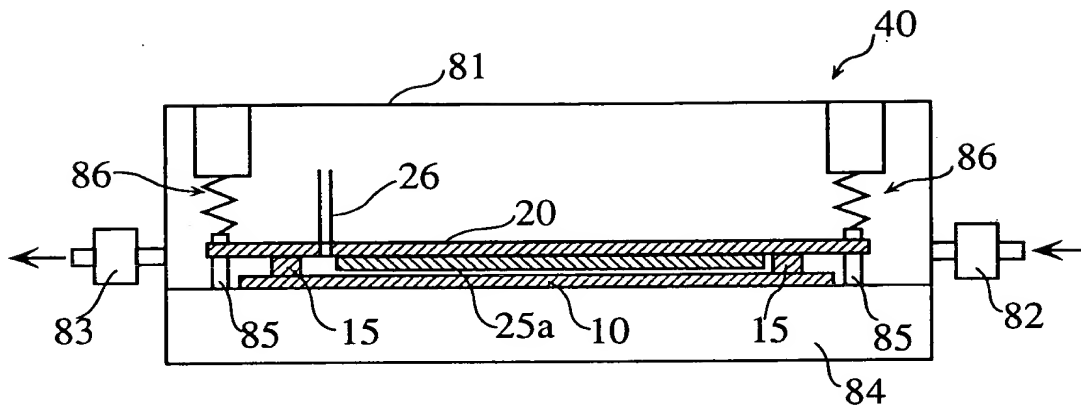


FIG.16B

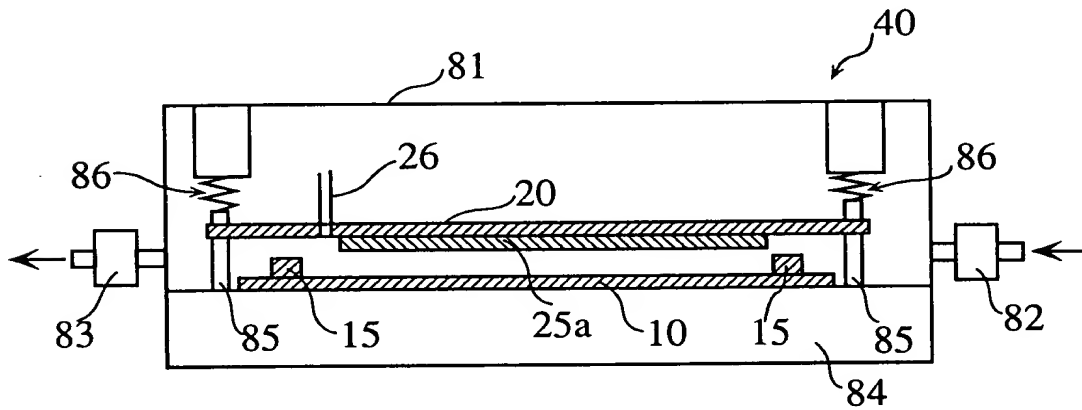


FIG.16C

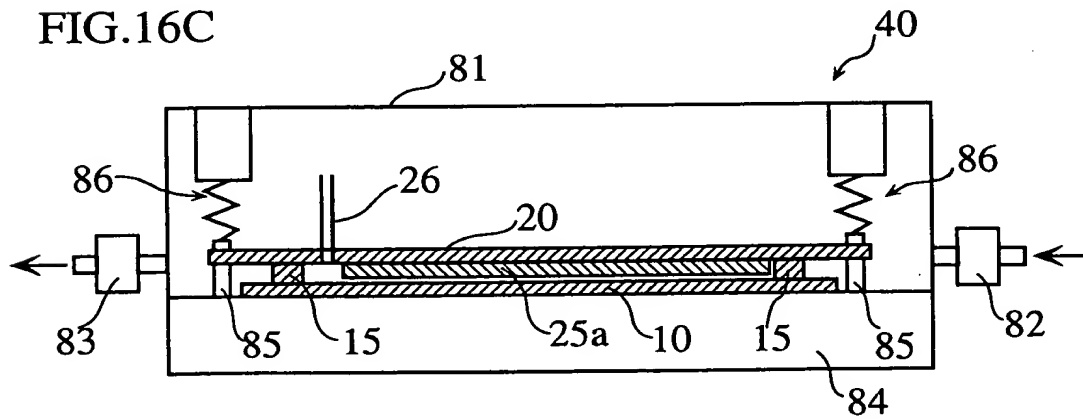


FIG. 17A

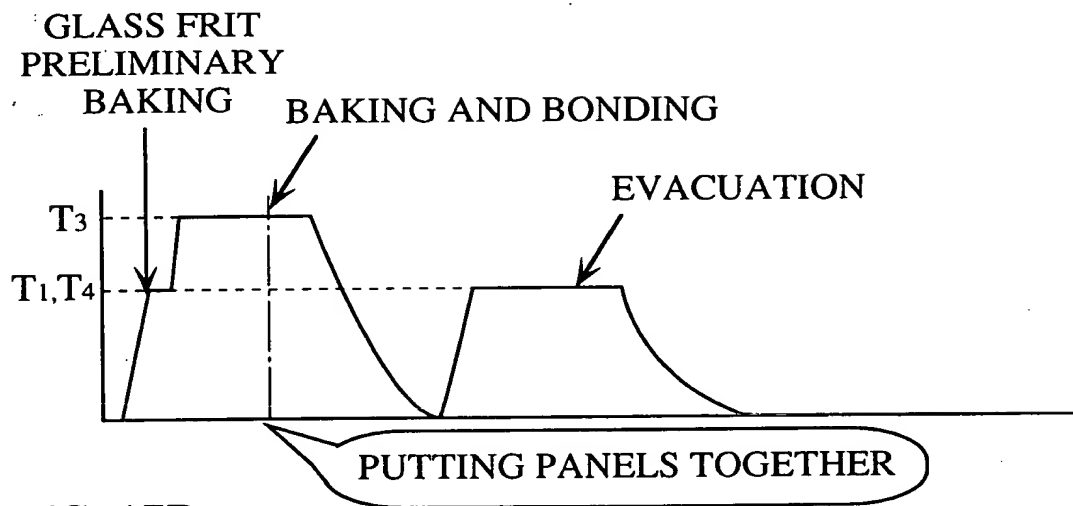


FIG. 17B

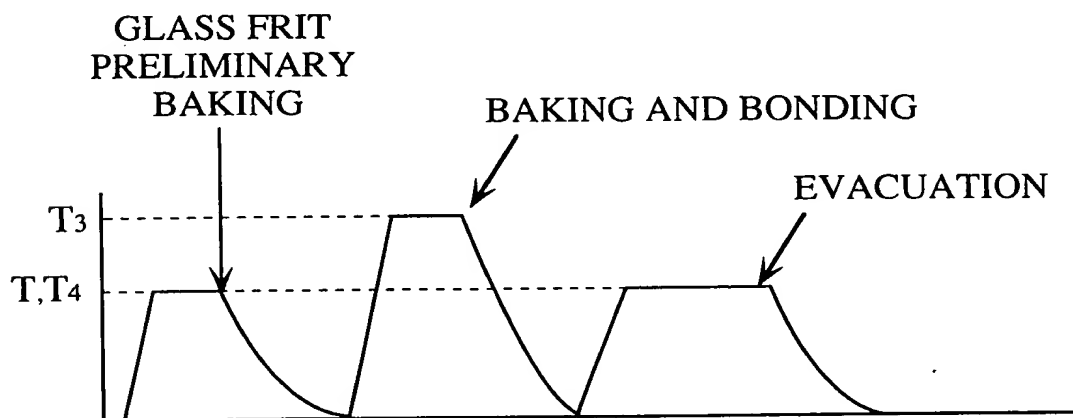


FIG. 18

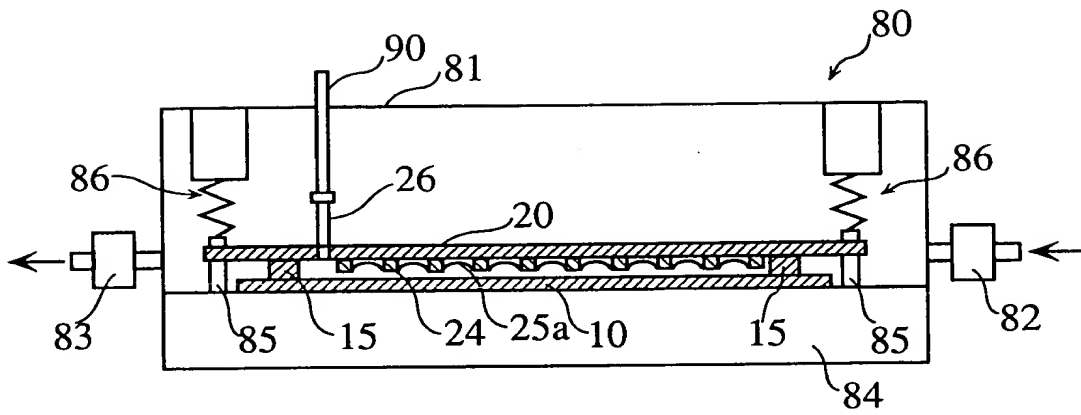


FIG. 18 is a cross-sectional view of the device of FIG. 17, showing the internal components and the housing. The device is shown in a cross-sectional view, with the housing (80) and the internal components (81, 82, 83, 84, 85, 86, 90, 20, 24, 25a, 26, 10, 15) clearly visible. The device is shown in a cross-sectional view, with the housing (80) and the internal components (81, 82, 83, 84, 85, 86, 90, 20, 24, 25a, 26, 10, 15) clearly visible.



FIG.19A

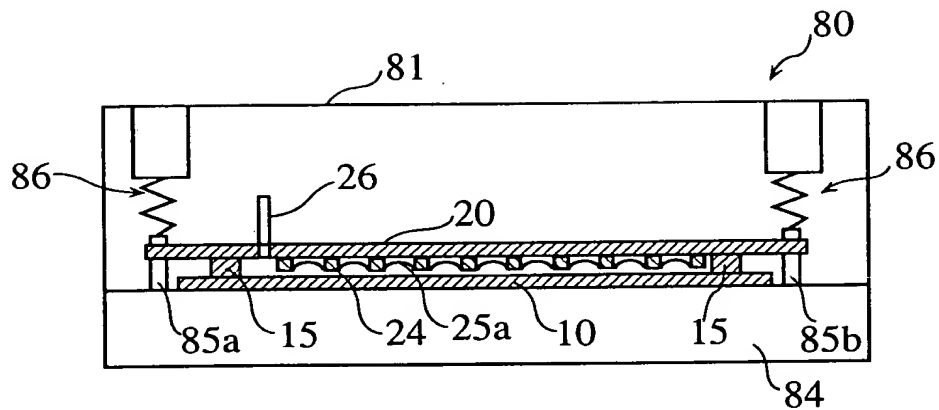


FIG.19B

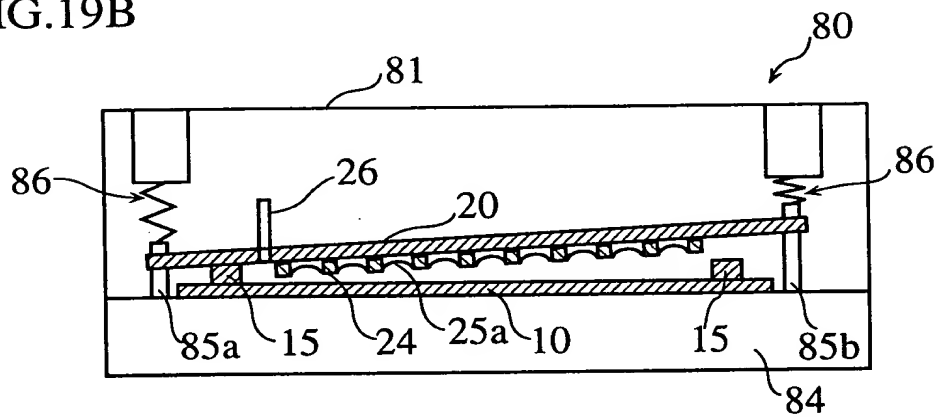


FIG.19C

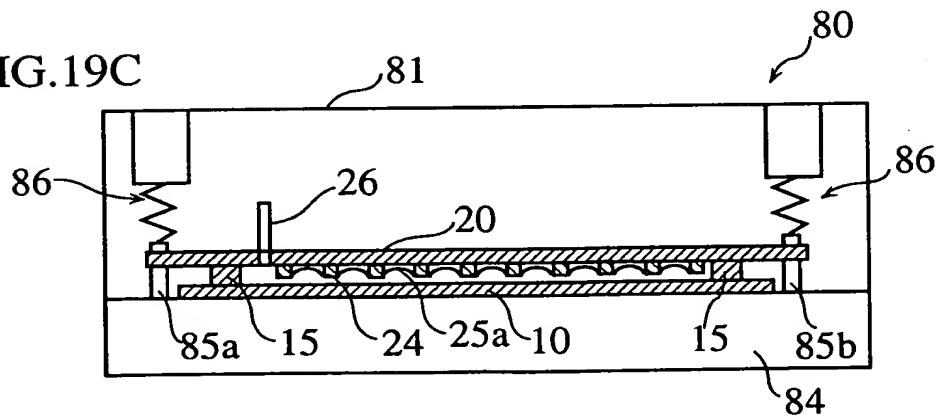


FIG.20

